

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSC0902NSI	**Issued**	14. August 2015
MA#	MA001013830		
Package	PG-TDSON-8-6	**Weight***	118.18 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.393	0.33	0.33	3322	3322
leadframe	non noble metal	iron	7439-89-6	0.038	0.03		320	
	inorganic material	phosphorus	7723-14-0	0.011	0.01		96	
	non noble metal	copper	7440-50-8	37.762	31.96	32.00	319521	319937
wire	noble metal	gold	7440-57-5	0.046	0.04	0.04	385	385
encapsulation	organic material	carbon black	1333-86-4	0.088	0.07		745	
	plastics	epoxy resin	-	6.251	5.29		52894	
	inorganic material	silicondioxide	60676-86-0	37.683	31.89	37.25	318854	372493
leadfinish	non noble metal	tin	7440-31-5	1.470	1.24	1.24	12437	12437
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1401	1401
solder	noble metal	silver	7440-22-4	0.016	0.01		131	
	non noble metal	tin	7440-31-5	0.012	0.01		105	
	non noble metal	lead	7439-92-1	0.592	0.50	0.52	5012	5248
heatspreader	non noble metal	iron	7439-89-6	0.011	0.01		96	
	inorganic material	phosphorus	7723-14-0	0.003	0.00		29	
	non noble metal	copper	7440-50-8	11.320	9.58	9.59	95785	95910
heat sink CLIP	non noble metal	iron	7439-89-6	0.022	0.02		189	
	inorganic material	phosphorus	7723-14-0	0.007	0.01		57	
	non noble metal	copper	7440-50-8	22.292	18.86	18.89	188621	188867
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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